Label Table

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<th>Label Text</th>
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<tbody>
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<td>ChangeMe!</td>
</tr>
<tr>
<td>002</td>
<td>ChangeMe!</td>
</tr>
</tbody>
</table>

Assembly Note

- **ZZ1**: These assemblies are ESD sensitive, ESD precautions shall be observed.
- **ZZ2**: These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- **ZZ3**: These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

PCB Number: TIDA-00284
PCB Rev: E1

PCB
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